Product / Process Change Notification



N° 2016-003-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Additional wafer diameter source: 12" for Modules with IGBT4 1200V (E4) technology

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 09. March 2016.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

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Product / Process Change Notification



N° 2016-003-A

SUBJECT OF CHANGE: Implementation of 12inch (300mm) wafer fab for IGBT products.

PRODUCTS AFFECTED: 1200V IGBT4 Modules.

Please refer to attached affected product list 1 cip16003a

REASON OF CHANGE: Capacity extension and increasing security of supply 1200V IGBT4

PRODUCT IDENTIFICATION: Individual production lot number on product label

TIME SCHEDULE:

■ First samples available: On request

■ Intended Start of delivery: July 2016 or directly after customer approval

ASSESSMENT: Additional chip source of the 12inch wafer fab in Villach, Austria and

Dresden, Germany. FE plants 12inch Villach and 12inch Dresden, 8inch Villach and 8inch Kulim produce as joint production and may be

delivered.

Locations of the backend productions of the IGBT modules are

unchanged.

The a.m. products / IGBT modules with IGBT chips from Villach, Dresden and Kulim each have identical specifications according to

JEDEC46: fit, form, function and reliability.

DOCUMENTATION: Affected product list 1_cip16003a

On request:

QPAC

Electrical Characterization

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